### I. SCOPE:

This specification applies to the Pb Free high current type SMD Common mode filter for MCM-9070M-SERIES

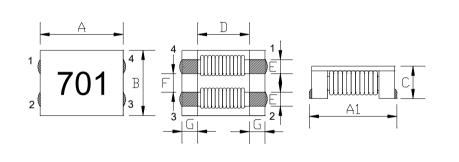
#### **PRODUCT INDENTIFICATION**

<u>MCM</u> - <u>9070M</u> - <u>701</u>



- ① Product Code
- ② Dimensions Code
- ③ Impedance Code

## (1) SHAPES AND DIMENSIONS



A: 9.0±0.5	mm
A1: 9.5±0.5	mm
B: 7.0±0.5	mm
C: 4.8Max.	mm
D: 5.6Typ.	mm
E: 1.5±0.2	mm
F: 2.0±0.2	mm
G: 1.7±0.2	mm

## (2) ELECTRICAL SPECIFICATIONS SEE TABLE 1

**TEST INSTRUMENTS** 

- Z : HP 4291B IMPEDANCE ANALYZER (or equivalent)
- RDC : CHROMA MODEL 16502 MILLIOHMMETER (or equivalent)
- I.R : CHROMA MODEL 19073 AC/DC/IR HIPOT TESTER (or equivalent)

# (3) CHARACTERISTICS

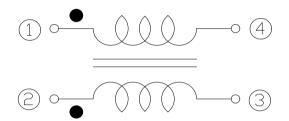
- (3)-1 Operate temperature range ......  $-40^{\circ}C \sim +125^{\circ}C$ 
  - (Including self temp. rise)
- (3)-2 Storage temperature range ......  $-40^{\circ}C \sim +125^{\circ}C$



## TABLE 1

MAGLAYERS PT/NO.	-	ince(Ω) 0MHz	Resistance RDC(Ω) Max.	Rated Current	Insulation Resistance	Rated Voltage
	Min.	Тур.	(1 line)	(A) Max.	(MΩ) Min.	(V)Max.
MCM-9070M-301	225	300	6m	6.0	10	80
MCM-9070M-501	450	600	8m	5.5	10	80
MCM-9070M-701	500	700	10m	5.0	10	80
MCM-9070M-102	750	1000	13m	4.0	10	80
MCM-9070M-222	1700	2200	60m	2.5	10	80
MCM-9070M-272	2000	2700	86m	2.0	10	80

# CHARACTERISTICS(REFERENCE)





### (4) RELIABILITY TEST METHOD

#### MECHANICAL

TEST ITEM	SPECIFICATION	TEST DETAILS	
Solder ability	The product shall be connected to the test	Apply cream solder to the printed circuit board .	
	circuit board by the fillet (the height is 0.2mm).	Refer to clause 8 for Reflow profile.	
Resistance to	There shall be no damage or problems.	Temperature profile of reflow soldering	
Soldering heat		© 300− soldering	
(reflow soldering)		Soldering 250 250 250 250 200 200 150 100 10	
Terminal strength	The terminal electrode and the ferrite must	Solder a chip to test substrate , and then laterally apply	
	not damaged.	a load 9.8N in the arrow direction.	
		Printed circuit board	
Strength on PC board	The terminal electrode and the ferrite must	Solder a chip to test substrate and then apply a load.	
bending	not damaged.	Test board:FR4 100×40×1mm R10 rl Fall speed:1mm/sec. 45 45 Dimensions in mm	
High	Impedance:Within±20% of the initial value.	After the samples shall be soldered onto the test circuit	
temperature	Insulation resistance and DC resistance on the	board,the test shall be done.	
resistance	specification(refer to clause 2-1) shall be met.	Measurement : After placing for 24 hours min.	
	The terminal electrode and the ferrite must not	Temperature : +125±2°C	
	damaged.	Applied voltage : Rated voltage	
		Applied current : Rated current	
		Testing time : 500±12 hours	



## (4) RELIABILITY TEST METHOD

#### MECHANICAL

TEST ITEM	SPECIFICATION	TEST DETAILS
Humidity	Impedance:Within±20% of the initial value.	After the samples shall be soldered onto the test circuit
resistance	Insulation resistance and DC resistance on the	board,the test shall be done.
	specification(refer to clause 2-1) shall be met.	Measurement : After placing for 24 hours min.
	The terminal electrode and the ferrite must not	Temperature : +60 $\pm 2^{\circ}$ C , Humidity : 90 to 95 %RH
	damaged.	Applied voltage : Rated voltage
		Applied current : Rated current
		Testing time : 500±12 hours
Thermal shock	Impedance:Within±20% of the initial value.	
	Insulation resistance and DC resistance on the	30 min.
	specification(refer to clause 2-1) shall be met.	$+125^{\circ}C$ $30 \text{ sed}$
	The terminal electrode and the ferrite must	
	not damaged.	-40°C +\/   \/
		30 min. Testing time:100 cycle
Low	Impedance:Within±20% of the initial value.	After the samples shall be soldered onto the test
temperature	Insulation resistance and DC resistance on the	circuit board,the test shall be done.
storage	specification(refer to clause 2-1) shall be met.	Measurement : After placing for 24 hours min.
	The terminal electrode and the ferrite must	Temperature : -40±2℃
	not damaged.	Testing time : 500±12 hours
Vibration	Impedance:Within±20% of the initial value.	After the samples shall be soldered onto the test circuit
	Insulation resistance and DC resistance on	board,the test shall be done.
	the specification(refer to clause 2-1)	Frequency : 10 to 55 Hz
	shall be met.	Amplitude : 1.52 mm
	The terminal electrode and the ferrite must	Dimension and times : X ,Y and Z directions
	not damaged.	for 2 hours each.
	· · · · · · · · · · · · · · · · · · ·	
Solderability	New solder More than 75%	Flux (rosin, isopropyl alcohol{JIS-K-1522}) shall be coated
		over the whole of the sample before hard, the sample shall
		then be preheated for about 2 minutes in a temperature
		of $130 \sim 150^{\circ}$ and after it has been immersed to a depth
		0.5mm below for 3±0.2 seconds fully in molten solder
		M705 with a temperature of $245\pm5$ °C. More than 75% of the
		electrode sections shall be couered
		with new solder smoothly when the sample is taken out
		of the solder bath.

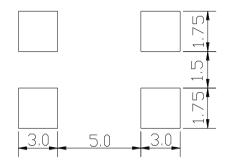


## (5) LAND DIMENSION (Ref.)

PCB: GLASS EPOXY t=1.6mm

#### (5)-1 LAND PATTERN DIMENSIONS

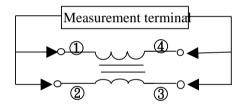
(STANDARD PATTERN) Unit:mm



# (6) TEST EQUIPMENT

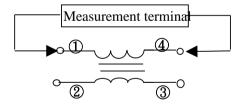
(6)-1 Impedance

Measured by using HP4291B RF Impedance Analyzer.



#### (6)-2 DC Resistance

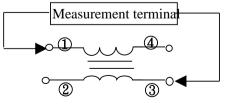
Measured by using Chroma 16502 milliohm meter.



(6)-3 Insulation Resistance

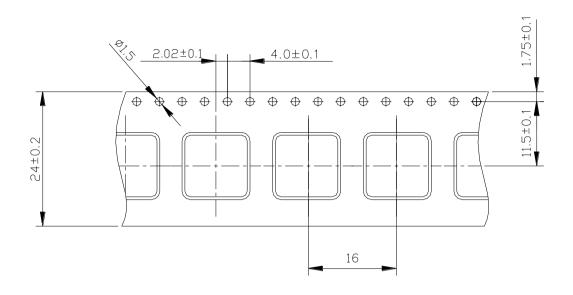
Measured by using Chroma 19073

Measurement voltage : 50v ,Measurement time : 60 sec.

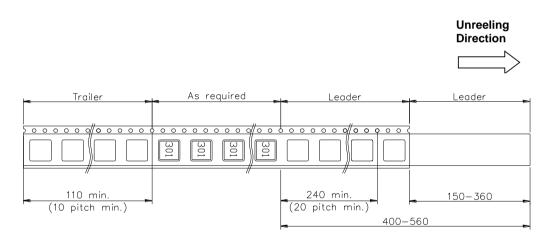




## (6) PACKAGING (6)-1 CARRIER TAPE DIMENSIONS (mm)

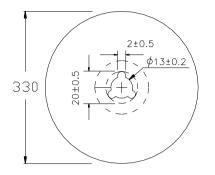


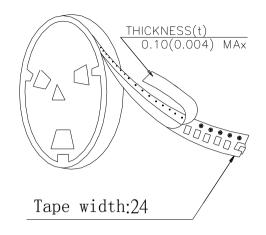
### (6)-2 TAPING DIMENSIONS (mm)





### (6)-3 REEL DIMENSIONS (mm)





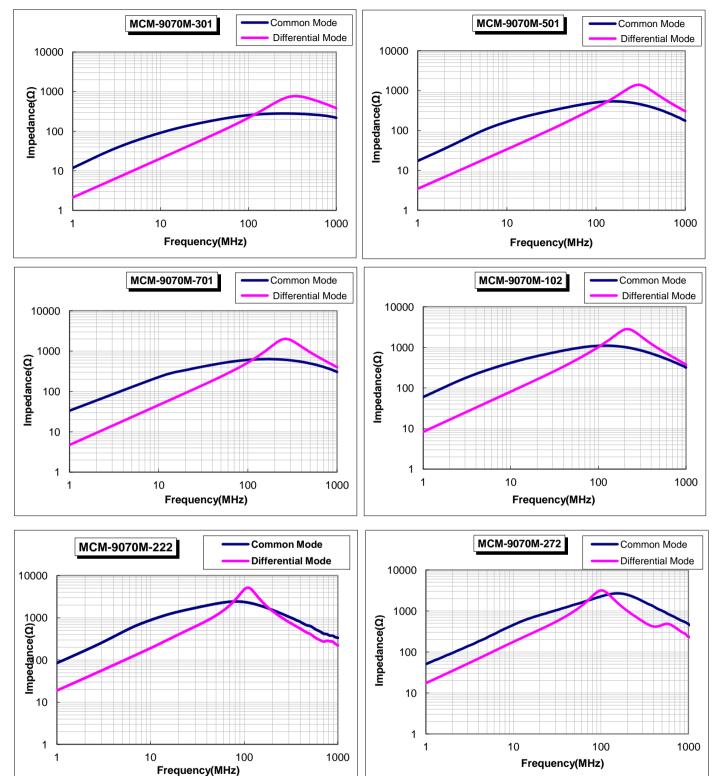
### (6)-4 QUANTITY

#### 700pcs/Reel

The products are packaged so that no damage will be sustained.

Please note that the contents may change without any prior notice due to reasons such as upgrading.





# **TYPICAL ELECTRICAL CHARACTERISTICS**



MCM-9070M-SERIES

**ATTACHMENT-1**